

····	1 100	Ownt Total	DB	Time stamp
L Number	Hits	Search Text	USPAT;	2003/12/12 20:02
1	676	438/398.ccls.		2003/12/12 20.02
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
2	32	438/398.ccls. and (metal near12 (textur\$3 texturi\$4 rough	USPAT;	2003/12/12 20:47
		roughen\$3 bump hump (surface adj area)))	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
3	219	438/677.ccls.	USPAT;	2003/12/12 20:38
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
4	19	438/677.ccls. and (metal near12 (textur\$3 texturi\$4 rough	USPAT;	2003/12/12 20:42
7	'3	roughen\$3 bump hump (surface adj area)))	US-PGPUB;	
		Toughengo bamp namp (samage daj dred)	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
_	22746	(retard\$3 retardation restrict\$3 reduc\$3 reduction prevent\$3	USPAT;	2003/12/12 21:03
5	23746		US-PGPUB;	2000/12/12 21:00
		limit\$3) near6 (seed\$3 nuclei nucleat\$3)	EPO; JPO;	
1			DERWENT:	
		100 100 100	IBM_TDB	2003/12/12 21:03
6	1030	((retard\$3 retardation restrict\$3 reduc\$3 reduction prevent\$3	USPAT;	2003/12/12 21.03
		limit\$3) near6 (seed\$3 nuclei nucleat\$3)) near12 (halogen	US-PGPUB;	
		halide chlori?e fluori?e bromi?e iodi?e "F.sub.2" "Cl.sub.2"	EPO; JPO;	
		"Br.sub.2" "I.sub.2" "CIF.sub.3")	DERWENT;	
			IBM_TDB	
7	6	(((retard\$3 retardation restrict\$3 reduc\$3 reduction prevent\$3	USPAT;	2003/12/12 21:04
	1	limit\$3) near6 (seed\$3 nuclei nucleat\$3)) near12 (halogen	US-PGPUB;	
		halide chlori?e fluori?e bromi?e iodi?e "F.sub.2" "Cl.sub.2"	EPO; JPO;	
		"Br.sub.2" "I.sub.2" "CIF.sub.3")) and (metal near12 (textur\$3	DERWENT;	
		texturi\$4 rough roughen\$3 bump hump (surface adj area)))	IBM_TDB	
8	37683	(retard\$3 retardation restrict\$3 reduc\$3 reduction prevent\$3	USPAT;	2003/12/12 20:53
		limit\$3) near6 (ammonia "NH.sub.3")	US-PGPUB;	
	1	,	EPO; JPO;	•
	e-		DERWENT;	
		·	IBM TDB	
9	46	(((retard\$3 retardation restrict\$3 reduc\$3 reduction prevent\$3	USPAT;	2003/12/12 20:49
ا "		limit\$3) near6 (seed\$3 nuclei nucleat\$3)) near12 (halogen	US-PGPUB	
		halide chlori?e fluori?e bromi?e iodi?e "F.sub.2" "Cl.sub.2"	EPO; JPO;	
		"Br.sub.2" "I.sub.2" "CIF.sub.3")) and ((retard\$3 retardation	DERWENT:	
		restrict\$3 reduc\$3 reduction prevent\$3 limit\$3) near6	IBM_TDB	İ
		(ammonia "NH.sub.3"))		
10	464	(retard\$3 retardation restrict\$3 reduc\$3 reduction prevent\$3	USPAT;	2003/12/12 20:54
10	461	limit\$3) near6 ((ammonia "NH.sub.3") near4 (deposit\$3	US-PGPUB;	2300, 12, 12 20.04
			EPO; JPO;	
		adsorp\$4 adher\$3))	DERWENT;	
			IBM_TDB	
١.,		//	USPAT;	2003/12/12 21:05
11	18	((retard\$3 retardation restrict\$3 reduc\$3 reduction prevent\$3		2003/12/12 21.03
		limit\$3) near6 ((ammonia "NH.sub.3") near4 (deposit\$3	US-PGPUB;	
		adsorp\$4 adher\$3))) same (W WN WN?sub.? tungsten)	EPO; JPO;	
			DERWENT;	
			IBM_TDB	00004045
12	30044	(retard\$3 retardation restrict\$3 reduc\$3 reduction prevent\$3	USPAT;	2003/12/12 21:03
1		limit\$3) near10 (seed\$3 nuclei nucleat\$3)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
ĺ			IBM_TDB	

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13	1466	((retard\$3 retardation restrict\$3 reduc\$3 reduction prevent\$3	USPAT;	2003/12/12 21:03
		limit\$3) near10 (seed\$3 nuclei nucleat\$3)) near12 (halogen	US-PGPUB;	
		halide chlori?e fluori?e bromi?e iodi?e "F.sub.2" "Cl.sub.2"	EPO; JPO;	
		"Br.sub.2" "I.sub.2" "CIF.sub.3")	DERWENT;	
			IBM_TDB	
14	11	1 ///	USPAT;	2003/12/12 21:04
		limit\$3) near10 (seed\$3 nuclei nucleat\$3)) near12 (halogen	US-PGPUB;	
		halide chlori?e fluori?e bromi?e iodi?e "F.sub.2" "Cl.sub.2"	EPO; JPO;	
		"Br.sub.2" "I.sub.2" "CIF.sub.3")) and (metal near12 (textur\$3	DERWENT;	
		texturi\$4 rough roughen\$3 bump hump (surface adj area)))	IBM_TDB	
15	20253	deposit\$3 near5 (W WN WN?sub.? tungsten)	USPAT;	2003/12/12 21:06
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
16	10032	(deposit\$3 near5 (W WN WN?sub.? tungsten)) and	USPAT;	2003/12/12 21:08
		((pretreat\$4 treat\$3 expos\$3 preparation preperatory	US-PGPUB;	
		prepar\$3) near12 (surface dielectric insulat\$3))	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
17	473	(deposit\$3 near5 (W WN WN?sub.? tungsten)) and	USPAT;	2003/12/12 21:09
		((pretreat\$4 treat\$3 expos\$3 preparation preperatory	US-PGPUB;	
		prepar\$3) near12 (surface dielectric insulat\$3) near20	EPO; JPO;	
		(halogen halide chlori?e fluori?e bromi?e iodi?e "F.sub.2"	DERWENT;	
		"Cl.sub.2" "Br.sub.2" "l.sub.2" "ClF.sub.3"))	IBM_TDB	000040400040
18	144	\	USPAT;	2003/12/12 21:09
		((pretreat\$4 treat\$3 expos\$3 preparation preperatory	US-PGPUB;	
		prepar\$3) near12 (dielectric insulat\$3) near20 (halogen	EPO; JPO;	
		halide chlori?e fluori?e bromi?e iodi?e "F.sub.2" "Cl.sub.2"	DERWENT;	
		"Br.sub.2" "I.sub.2" "CIF.sub.3"))	IBM_TDB	0000/40/40 04:40
19	16	4552783.URPN.	USPAT	2003/12/12 21:13
20	3	5502005.URPN.	USPAT	2003/12/12 21:36